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Product Change Notification - JAON-14OICS710

Date: 17 Oct 2016
Product Category: 8-bit Microcontrollers; 16-bit Microcontrollers and Digital Signal Controllers
Notification subject: CCB 2697 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 44L QFN (8x8x0.9mm) package at MTAI assembly site.
Notification text: **PCN Status:**
 Final notification

Microchip Parts Affected:
 Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
 Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 44L QFN (8x8x0.9mm) package at MTAI assembly site.

Pre Change:
 Using gold (Au) bond wire

Post Change:
 Using gold (Au) bond wire or palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI assembly site	MTAI assembly site
Wire material	Au wire	Au wire or CuPdAu wire
Die attach material	3280	3280
Molding compound material	G700LTD	G700LTD
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and qualify Palladium coated copper with gold flash (CuPdAu) bond wire

Change Implementation Status:

In Progress

Estimated First Ship Date:

October 22, 2016 (Date code: 1642)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2016				->	September 2016					October 2016				
	27	28	29	30		35	36	37	38	39	40	41	42	43	44
Workweek															
Initial PCN Issue Date			X												
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date												X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

July 19, 2016: Issued initial notification.

September 22, 2016: Issued final notification. Attached the qualification report. Provided estimated first ship date on October 22, 2016.

October 17, 2016: Re-issued the final notification to notify all affected customers.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_JAON-14OICS710_Qual report.pdf](#)
- [PCN_JAON-14OICS710_Affected_CPN.pdf](#)
- [PCN_JAON-14OICS710_Affected_CPN.xlsx](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-14OICS710
CATALOG_PART_NBR
DSPIC30F2023-20E/ML
DSPIC30F2023-30I/ML
DSPIC30F2023T-30I/ML
DSPIC30F2023T-30V/MLD31
DSPIC30F3010-20I/ML
DSPIC30F3010-30I/ML
DSPIC30F3010T-30I/ML
DSPIC30F3011-10I/MLB24
DSPIC30F3011-20E/ML
DSPIC30F3011-20I/ML
DSPIC30F3011-30I/ML
DSPIC30F3011T-10I/MLB21
DSPIC30F3012-20E/ML
DSPIC30F3012-20I/ML
DSPIC30F3012-30I/ML
DSPIC30F3012T-20I/ML
DSPIC30F3013-20E/ML
DSPIC30F3013-20I/ML
DSPIC30F3013-30I/ML
DSPIC30F3013-30I/MLB31
DSPIC30F3013T-20I/ML
DSPIC30F3013T-30I/ML
DSPIC30F3013T-30I/MLB31
DSPIC30F3014-20E/ML
DSPIC30F3014-20I/ML
DSPIC30F3014-30I/ML
DSPIC30F3014-30I/MLA31
DSPIC30F3014T-30I/MLA31
DSPIC30F4011-20E/ML
DSPIC30F4011-20I/ML
DSPIC30F4011-30I/ML
DSPIC30F4012-20E/ML
DSPIC30F4012-20I/ML
DSPIC30F4012-30I/ML
DSPIC30F4013-20E/ML
DSPIC30F4013-20I/ML
DSPIC30F4013-30I/ML
DSPIC30F4013-30I/MLB31
DSPIC30F4013T-30I/ML
DSPIC30F4013T-30I/MLB31
PIC16F747-I/ML
PIC16F747T-I/ML
PIC16F777-I/ML

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Affected Catalog Part Numbers (CPN)

PCN_JAON-14OICS710
CATALOG_PART_NBR
PIC16F77-I/ML
PIC16F874A-I/ML
PIC16F874AT-I/ML
PIC16F877A-E/ML
PIC16F877A-I/ML
PIC16F877AT-I/ML
PIC16F884-E/ML
PIC16F884-I/ML
PIC16F884T-I/ML
PIC16F887-E/ML
PIC16F887-I/ML
PIC16F887T-I/ML
PIC16F914-E/ML
PIC16F914-I/ML
PIC16F914T-I/ML
PIC16F917-E/ML
PIC16F917-I/ML
PIC16F917T-I/ML
PIC16LF777-I/ML
PIC16LF874A-I/ML
PIC16LF877A-I/ML
PIC18F4220-E/ML
PIC18F4220-I/ML
PIC18F4220T-I/ML
PIC18F4221-E/ML
PIC18F4221-I/ML
PIC18F4320-E/ML
PIC18F4320-I/ML
PIC18F4320T-I/ML
PIC18F4321-E/ML
PIC18F4321-I/ML
PIC18F4331-I/ML
PIC18F4410-I/ML
PIC18F4420-E/ML
PIC18F4420-I/ML
PIC18F4420T-I/ML
PIC18F4423-E/ML
PIC18F4423-I/ML
PIC18F4423T-I/ML
PIC18F442-I/ML
PIC18F4431-I/ML
PIC18F4450-I/ML
PIC18F4455-I/ML

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Affected Catalog Part Numbers (CPN)

PCN_JAON-14OICS710
CATALOG_PART_NBR
PIC18F4458-I/ML
PIC18F4480-E/ML
PIC18F4480-I/ML
PIC18F4480T-I/ML
PIC18F4510-E/ML
PIC18F4510-I/ML
PIC18F4510T-I/ML
PIC18F4515-I/ML
PIC18F4520-E/ML
PIC18F4520-I/ML
PIC18F4520T-E/ML
PIC18F4520T-I/ML
PIC18F4523-E/ML
PIC18F4523-I/ML
PIC18F4523T-I/ML
PIC18F4525-E/ML
PIC18F4525-I/ML
PIC18F4525T-I/ML
PIC18F452-E/ML
PIC18F452-I/ML
PIC18F452T-I/ML
PIC18F4550-I/ML
PIC18F4553-I/ML
PIC18F4580-E/ML
PIC18F4580-I/ML
PIC18F4580T-I/ML
PIC18F4585-E/ML
PIC18F4585-H/ML
PIC18F4585-I/ML
PIC18F4585-I/MLC01
PIC18F4585T-I/ML
PIC18F4610-I/ML
PIC18F4620-E/ML
PIC18F4620-I/ML
PIC18F4620T-I/ML
PIC18F4680-E/ML
PIC18F4680-H/ML
PIC18F4680-I/ML
PIC18F4680T-I/ML
PIC18F4682-E/ML
PIC18F4682-I/ML
PIC18F4685-E/ML
PIC18F4685-I/ML

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Affected Catalog Part Numbers (CPN)

PCN_JAON-14OICS710
CATALOG_PART_NBR
PIC18F4685T-I/ML
PIC18LF4220-I/ML
PIC18LF4220T-I/ML
PIC18LF4221-I/ML
PIC18LF4221T-I/ML
PIC18LF4320-I/ML
PIC18LF4320T-I/ML
PIC18LF4320T-I/MLC06
PIC18LF4321-I/ML
PIC18LF4331-I/ML
PIC18LF4410-I/ML
PIC18LF4420-I/ML
PIC18LF4420T-I/ML
PIC18LF4423-I/ML
PIC18LF4423T-I/ML
PIC18LF442-I/ML
PIC18LF442T-I/ML
PIC18LF4431-I/ML
PIC18LF4450-I/ML
PIC18LF4450T-I/ML
PIC18LF4455-I/ML
PIC18LF4458-I/ML
PIC18LF4480-I/ML
PIC18LF4480T-I/ML
PIC18LF4510-I/ML
PIC18LF4510T-I/ML
PIC18LF4515-I/ML
PIC18LF4520-I/ML
PIC18LF4520T-I/ML
PIC18LF4523-I/ML
PIC18LF4523T-I/ML
PIC18LF4525-I/ML
PIC18LF4525T-I/ML
PIC18LF452-I/ML
PIC18LF452T-I/ML
PIC18LF4539-I/ML
PIC18LF4550-I/ML
PIC18LF4553-I/ML
PIC18LF4580-I/ML
PIC18LF4585-I/ML
PIC18LF4585T-I/ML
PIC18LF4610-I/ML
PIC18LF4620-I/ML

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Affected Catalog Part Numbers (CPN)

PCN_JAON-14OICS710
CATALOG_PART_NBR
PIC18LF4620-I/ML035
PIC18LF4620T-I/ML
PIC18LF4620T-I/ML035
PIC18LF4680-I/ML
PIC18LF4682-I/ML
PIC18LF4685-I/ML
PIC18LF4685T-I/ML